Product Change Notification - JAON-27DTJD589

Date: 07 Oct 2016

Product Category: 8-bit Microcontrollers

Notification subject: CCB 2698 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Pre Change:
Using gold (Au) bond wire

Post Change:
Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI	MTAI
Wire material	Au wire	CuPdAu wire
Die attach material	3280	3280
Molding compound material	G700LTD	G700LTD
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
October 30, 2016 (Date code: 1643)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.
Time Table Summary:

	October 2016			
Workweek	40	41	42	43
Qual Report Availability	X			
Final PCN Issue Date	X			
Estimated Implementation Date				X

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
October 7, 2016: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-27DTJD589_Qual_Report.pdf
PCN_JAON-27DTJD589_Affected_CPN.pdf
PCN_JAON-27DTJD589_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Products | Applications | Design Support | Training | Sample and Buy | About Us | Contact Us | Legal | Investors | Careers | Support

©Copyright 1998-2016 Microchip Technology Inc. All rights reserved. Shanghai ICP Recordal No.09049794

JAON-27DTJD589 - CCB 2698 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-27DTJD589
CATALOG_PART_NBR
PIC16F1526-E/MR
PIC16F1526-I/MR
PIC16F1526T-I/MR
PIC16F1527-E/MR
PIC16F1527-I/MR
PIC16F1527T-I/MR
PIC16F1946-E/MR
PIC16F1946-I/MR
PIC16F1946T-I/MR
PIC16F1947-E/MR
PIC16F1947-I/MR
PIC16F1947T-I/MR
PIC16LF1526-E/MR
PIC16LF1526-I/MR
PIC16LF1526T-I/MR
PIC16LF1527-E/MR
PIC16LF1527-I/MR
PIC16LF1527T-I/MR
PIC16LF1946-E/MR
PIC16LF1946-I/MR
PIC16LF1946T-I/MR
PIC16LF1947-E/MR
PIC16LF1947-I/MR
PIC16LF1947T-I/MR
PIC18F65K22-E/MR
PIC18F65K22-I/MR
PIC18F65K22T-E/MR
PIC18F65K22T-I/MR
PIC18F65K80-E/MR
PIC18F65K80-H/MR
PIC18F65K80-I/MR
PIC18F65K80T-I/MR
PIC18F65K90-E/MR
PIC18F65K90-I/MR
PIC18F65K90T-I/MR
PIC18F66K22-E/MR
PIC18F66K22-I/MR
PIC18F66K22T-E/MR
PIC18F66K22T-I/MR
PIC18F66K80-E/MR
PIC18F66K80-H/MR
PIC18F66K80-I/MR
PIC18F66K80T-I/MR

JAON-27DTJD589 - CCB 2698 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 64L QFN (9x9x0.9mm) package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-27DTJD589
CATALOG_PART_NBR
PIC18F66K90-E/MR
PIC18F66K90-I/MR
PIC18F66K90T-I/MR
PIC18F67K22-E/MR
PIC18F67K22-I/MR
PIC18F67K22-I/MRRSL
PIC18F67K22T-I/MR
PIC18F67K22T-I/MRRSL
PIC18F67K90-E/MR
PIC18F67K90-I/MR
PIC18F67K90-I/MRRSL
PIC18F67K90T-I/MR
PIC18LF65K80-I/MR
PIC18LF65K80T-I/MR
PIC18LF66K80-I/MR
PIC18LF66K80T-I/MR